Product End-of-Life Disassembly Instructions

Product Category: Desktop PC

Marketing Name / Model
[List multiple models if applicable.]

HP Elite Mini 800 G9 Desktop PC/ HSC-Q001DM

Purpose: *The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).*

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	**Components and parts requiring selective treatments**	**Quantity of items included in product**
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	*[x] Main board (MB) PCB [x] Solid state drive (SSD) PCB [ ] Wireless module PCB [x] External power supply (EPS) PCB [x] External Keyboard (KB) [x] External Mouse [x] Option-1 card : Type-C thunderbolt card PCB [x] Option-2 card : Dual USB-A card PCB [x] RAM PCB*	*9*
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries		*1*
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	*Battery(ies) are attached to the product by: [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain ______*	*0*
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		*0*
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	*[ ] Panel LCD*	*0*
Cathode Ray Tubes (CRT)		*0*
Capacitors / condensers (Containing PCB/PCT)		*0*

Item Description	**Components and parts requiring selective treatments**	**Quantity of items included in product**
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	*[ ] Power Supply capacitor(s) or condenser(s)*	*0*
External electrical cables and cords	*[x] AC power cord* *[ ] Audio, video or data cables* *[ ] Other:*	*1*
Gas Discharge Lamps		*0*
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		*0*
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		*0*
Components and waste containing asbestos		*0*
Components, parts and materials containing refractory ceramic fibers		*0*
Components, parts and materials containing radioactive substances		*0*
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		*0*

2.0 Tools Required

List of the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	**Tool Size (if applicable)**
[x] Screwdriver-1	TORX T15
[x] Screwdriver-2	*PHILLIPS #1*
[x] Screwdriver-3	Hexagon socket wrench 5mm

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

1. *Removed TOP Case*
2. *Removed Front Cover*
3. *Removed HDD Bracket*

4. *Removed HDD*
5. *Removed Main Fan*
6. *Removed Thermal Module*
7. *Removed Motherboard*
8. *Removed Button Case*
9. *Removed Option Card*
10. *Removed SSD and Wireless module*
11. *Removed RAM PCB and RTC battery*

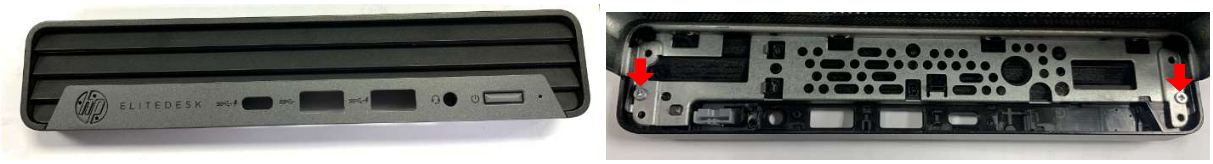
NOTE - For disassembly instructions of the external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the links below:

- Generic External Power Supply (EPS)
- **Generic** Keyboard
- **Generic** Mouse
- **Generic** cables and cords

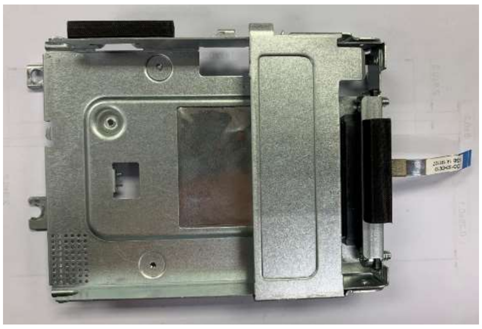
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Removed TOP Case is toolless (hand screw)

2. Removed Front Cover with PHILLIPS #1 screw driver.



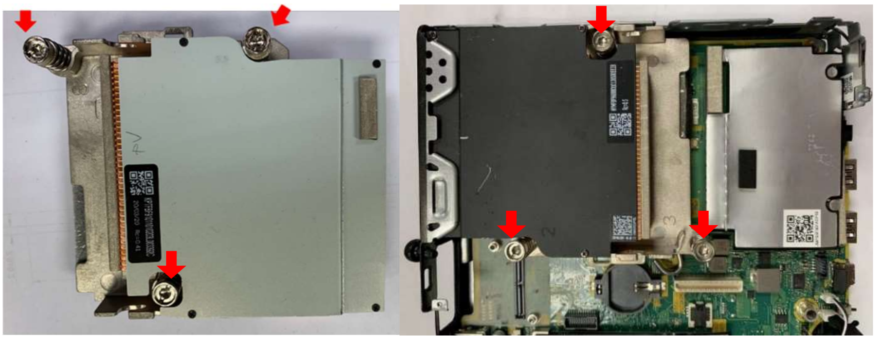
3. Removed HDD Bracket with T15 screw driver.



4. Removed HDD Bracket with PHILLIPS #1 screw driver.

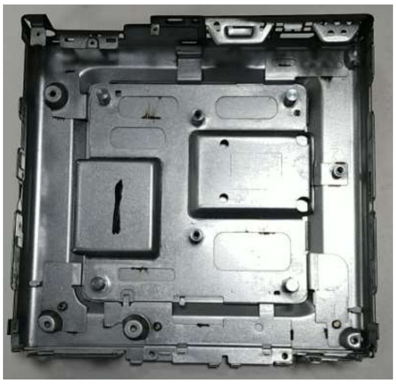
5. Removed Main Fan (toolless)

6. Removed Thermal Module with T15 screw driver.

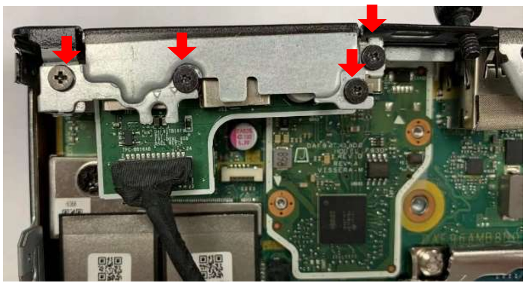


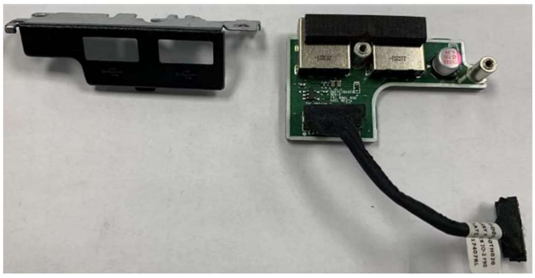
7. Removed Motherboard with T15 screw driver.

8. Removed Bottom Case

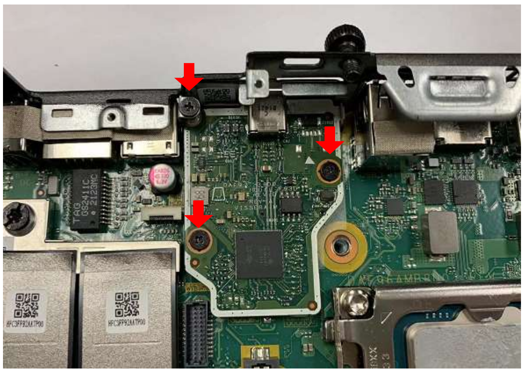


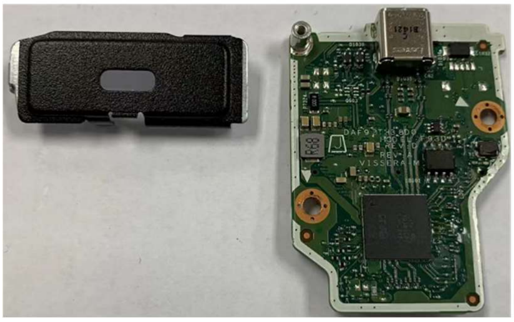
9. Removed Option Card with PHILLIPS #1 screw driver.





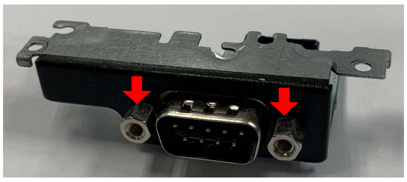
Dual USB-A card PCB





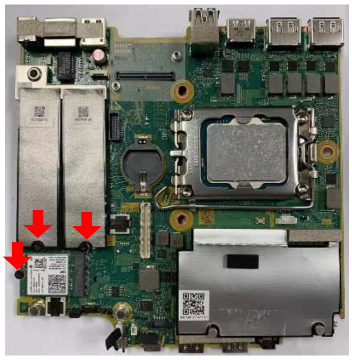
Type-C thunderbolt card PCB

Removed Option-2 serial port Card with hexagon socket wrench 5mm screw driver



Serial port card PCB

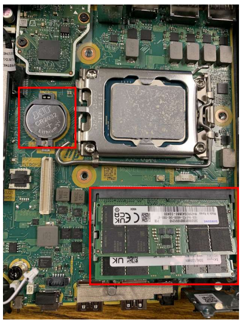
10. Removed SSD PCB and Wireless Module PCB with PHILLIPS #1 screw driver.



SSD PCB

Wireless Module PCB

11. Removed RAM PCB and RTC battery



RAM PCB

RTC battery